

**IN THE CLAIMS:**

Kindly amend the claims as follows:

1. (Amended) A multiple force tool for applying pressure to circuit board components comprising:

A2 first, second and third support channels for supporting first, second and third horizontally extending arms over a circuit board having multiple components;

a plurality of pressure cylinders supported by said horizontally extending arms over each of said components; and

means connected to said pressure cylinders for extending a pressure foot of said cylinders to a position for applying a bonding force against said components providing pressure contact between board components and said circuit board.

Claim 3,

line 3, change "transducers" to --cylinders--.

Kindly cancel claims 5-10.

Kindly insert new method claims 11-15, as follows:

11. A method for applying a bonding pressure to circuit board components comprising:

supporting first, second and third pressure cylinders over components on said circuit board; and

supplying a source of pressurized air to said pressure cylinders whereby a foot of said pressure cylinders extends to apply a force against said components.

A3  
cont.  
--12. The method for applying pressure to said pressure cylinders according to claim 11 wherein said step of supporting includes a step of positioning said pressure cylinders along said first and second axes to align said cylinder feet with a respective component on said circuit board.

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--13. The method for applying pressure to said pressure cylinders according to claim 12 wherein said positioning step includes positioning arms for supporting said pressure cylinder along channels which are located along said axes.

--14. The method according to claim 11 wherein said pressurized air is supplied as a timed pulse wherein said pressure is applied to said components for a fixed duration of time.

--15. The method according to claim 11 wherein said step of supplying said timed pulse of pressurized air includes regulating the time pulse of air.--